

Amendment

U.S. Patent Application No. 10/829,362

Amendments to the Specification:

Please replace the paragraph at page 4, lines 6-12, with the following replacement paragraph:

FIG. 2 illustrates an application with four memory modules 5. In this case, two of the memory modules 5 can be populated with memory chips 8 on both sides, and two are populated with memory chips 8 on one side. However, the contact areas can be disposed to produce a force-locking thermally conductive connection, even if the total thickness of memory chip 8 and circuit board 7 varies. Therefore, [[a]] flexible ~~connection~~ connections 15 can be provided for the contact areas 12. An insulation layer 13 on the contact area 12 can prevent the short-circuiting of non-insulated lines on the memory module.

Please insert the following paragraphs at page 6, line 16, after “14 Cooling fins”:

15 Connection

16 Peltier element